

IN THE SPECIFICATION

Please amend Table 1 at page 25 as follows:

		Embodi- ment 1	Embodi- ment 2	Embodi- ment 3	Embodi- ment 4	Embodi- ment 5	Embodi- ment 6	Embodi- ment 7	Embodi- ment 8
Materials used		Short fiber G F	Continuous fiber G F	←	←	←	←	Short fiber G F	<u>Continuous fiber G F</u>
		Crystalline resin	Crystalline resin	←	←	←	←	Non- crystalline resin	<u>Crystalline resin</u>
Fiber length(mm)		0.5	4	←	←	←	←	0.5	4
Amount of fiber added (wt%)		30	20	←	←	←	←	30	<u>20</u>
Molding method		Hollow molding	←	←	Injection molding	Hollow molding	←	←	←
Die temperature	At shaping	[[130]]135	←	←	←	←	←	[[←]]130	←
	At holding	125	←	←	←	115	135	-	<u>100</u>
	At cooling	60	←	←	←	←	←	←	<u>60</u>
Die surface		Mirror finishing	←	Embossing	Mirror finishing	←	←	←	←
Average surface roughness (μm)		2	3	-	2	4	2	2	<u>10</u>
Image clarity		Good	Good	-	Good	Good	Good	Good	<u>Poor</u>
Die transcription rate		-	-	95	-	-	-	-	=
Shrinkage and warpage		○	○	○	○	○	○	○	○